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Application Note

AN000536

TDC-GP30-F01

How to Add Custom Code

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1 Introduction

TDC-GP30 is a system on chip solution for ultrasonic flow metering. Using its integrated CPU and code memory, TDC-GP30 can be operated with a dedicated firmware for result evaluation and operation control.

The TDC-GP30-F01 variant comes already with a preprogrammed **ams** firmware for flow and temperature calculation. The main part of this firmware is protected, but there is also an open memory space that allows a user to add some custom code.

This application note describes how a customized code is added to the open part of the **ams** flow firmware. The firmware user code is referred to as FWU. The relevant file is named GP30Y_A1.D2.11.xx.

Following the naming convention, the modified file should be saved with a different name such as A1.C2.11.YY, where C indicates it is a custom version.

Figure 1 shows the basic flow diagram of the main program and the various points where custom code can be added.



Figure 1: ams Firmware Open Part - FWU



For illustrative purposes, a very simple example is used:

With each TOF measurement a counter (NUMBER_OF_RUNS) is increased. The counter is reset every time it reaches a specified level (MAX_NUMBER) and a pulse is generated on GPIO0 that lasts until the next CPU call.



Information

The pulse interface needs to be turned off, as the GPIO0 is used.

2 **Preparation**

2.1 Project Files

Please do not make any changes in the system folder. Copy all the files to your private folder if you are planning to make changes to the code. The relevant files are:

- The is the modified assembler source file, based on the default file GP30Y_A1.D2.11.04.asm. (in our example: GP30Y_A1.C2.11.01.asm)
- The compiled .hex-file, that is downloaded into the chip. (in our example: GP30Y_A1.C2.11.01.hex)
- The firmware data file, including configuration and other data. It is also downloaded into the chip. (in our example: GP30Y_A1.C2.11.01.dat)
- .h files are headers containing the register descriptions of the device. They are needed for successful compilation (typically those are GP30Y_A1.D2.11.04.h, GP30Y_REG_A1.2.h, and GP30Y_ROM_A1.common.h).

2.2 Open the .asm Example

• Launch GP30 evaluation software and select Assembler in Firmware menu.

Figure 2:

Firmware Menu > Assembler



am

2.3 Assembler File Description

- Open .asm file and adjust date, file name, author and notes on changes
- Tip: double click on the #include files to show them on the menu tab.
- Search for the section of the source code that is designated to custom code
- Add your code. Small snippets can be inserted directly. Larger code sections should be accessed by jumping to subroutines.

Figure 3 : **Spots for Custom Code**



- Custom code section 1: Between error handling and post-processing
- 2 Custom code section 2: Between post processing and end of main program

3 Assembler Programming

3.1 Declarations

First, variables and constants should be declared. In our example, these are:

- NUMBER_OF_RUNS. Counts the number of TOF measurements
- MAX_NUMBER. If NUMBER_OF_RUNS exceeds this limit then the GPIO is set and the counter is reset to zero.
- DEBUG_ADDR_xx determines the USER RAM address for debugging. DEBUG_CONTENT_xx uses different values for debugging.
- OWN_FLAG is a debug register used to store the content of the BNR_TOF_UPD flag in register SRR_FEP_STF. This indicates whether a new TOF measurement is available. The mirror is needed because the MK_PP routine resets this flag.
- BNR_GPIO. Defines the bit number of the mirrored flag in the mirror register

Figure 4: Parameter Declaration

63 CONST NUMBER_OF_RUNS 0x38 ; RAM address actual counter value 64 CONST MAX_NUMBER 0x10 ; Maxixum counter value	
64 CONST MAX_NUMBER 0x10 ; Maxixum counter value	
65 CONST DEBUG_ADDR_01 0x40 ; RAM address f a debug value	
66 CONST DEBUG_CONTENT_01 0x101010 ; Arbitrary debug value	
67 CONST OWN_FLAG 0x42 ; Own Flag Register, mirrors BNR_TOF_UPD flag in register SR	R_FEP_STF
68 CONST BNR GPIO 0 ; Bit Number of OWN FLAG register	
69	

After the error handling we added a code snippet that:

- Clears the GPIO0, setting it low
- Copies the value of the TOF update flag into our own flag

Figure 5: Custom Code 1

```
101
    ; Clear GPIO0 with the (next) CPU call
               SHR GPO
102
       ramadr
103
               r, BNR_GPO0_OUT
       bitclr
                             ;
104
               SRR FEP STF
                             ;-- Set RAM Address to SRR_FEP_STF
       ramadr
105
               r, BNR_TOF_UPD, 2
106
       skipBitC
                            ;-- Check US_TOF_UPD Flag
107
               OWN_FLAG
                             ;-- Save as OWN_FLAG (SRR_FEP_STF will be reset by MK_PP
       amadr
   108
109
```



After the post-processing we added a jump into the major custom subroutine. The subroutine does the following:

- Check, whether a TOF measurement triggered the CPU
- If yes, increase the counter
- Compare the counter with the maximum. If this is exceed, jump into the event routine
- The event routine writes the debug value. This is just for demonstration how you can debug
- The counter is reset to zero
- GPIO0 is set HIGH
- The OWN flag is reset

Figure 6: Main Custom Subroutine

```
173
174
     MK CUSTOM CODE:
175
                      --- Counts the TOF measurements
     ; -----
                   OWN_FLAG ;-- Set RAM Address to SRR_FEP_STF
r, BNR_GPIO, 1 ;-- Check US_TOF_UPD Flag
176
         ramadr
177
178
         skipBitC
                   MK_CUSTOM_TOF
         jsub
179
180
         jsubret
     ; ----- END MK_CUSTOM_CODE
181
182
183
     MK_CUSTOM_TOF:
       - _ _ _ _ _ _ _ _ _ _ _ _ _ _ Counts the TOF measurements
184
     ι.
185
         ramadr
                   NUMBER_OF_RUNS
                                      ;
186
         incr
                                      ; incr counter by 1
187
188
                   y,r
         move
         clear
189
                   x, MAX_NUMBER
190
         add
191
         sub
                                      ; check whether maximum number is reached
                   y,x
192
         skipPos
                   MK_CUSTOM_EVENT
193
         isub
194
         ;nop
195
196
         jsubret
197
        ----- END MK_CUSTOM_TOF
     3
198
199
     MK_CUSTOM_EVENT:
                   y, DEBUG_CONTENT_01
DEBUG_ADDR_01
                                       ; Write 0x101010 to address 40
200
         move
201
         ramadr
                                         ; for debugging to prove that this sequence was reached
202
         move
                   r, y
203
204
                   NUMBER_OF_RUNS
         ramadr
                                      ;
205
         clear
                                      ; reset counter
206
207
        ----- Set BNR_GPIO bit and OWN_FLAG register
     1 - E
208
209
         ramadr
                   OWN FLAG
                                   ; clear custom OWN_FLAG
                   r, BNR_GPIO
         bitclr
210
211
212
         ramadr
                   SHR_GPO
                                      ; set GPIO0 and reset takes about ~200ns
                   r, BNR_GPO0_OUT
         bitset
213
214
         jsubret
215
          ----- END MK CUSTOM EVENT
     5
216
217
```



3.2 Compile

- Assembler menu, Compile (or press F5)
- After pressing Compile and Download, the output window should show "Processing was successful" and "Hex-File transferred to Download window". The Compile Options is used to configure whether after each compiling the download is executed.

Figure 7:

Assembler Output

	203 204 205 < Output	ramadr	NUMBER_OF_RUNS	; · reset counter	~	
GP30 Assembler, acam messelectronic gmbh INFO: T:\Marketing\Applikationsschriften\GP30-F01 AN536 Add custom firmware\ProgramRessources\GP30Y_A1.C2.11.01.asm: Process was successful Hex-File transfered to Download window		1.C2.11.01.asm: Processing				



3.3 Download Code to the Target

Attention

Be sure that the TDC-GP30-F01 is idle.

- Open .asm file and .dat file.
- Press button "Verify FW".
- Copy "Calculated Checksum by GP30" to field "Checksum FWA manual entry".
- Press button "Download FW Code & Data".



Information

The assembler transfers the compiled code directly into the download window. So the new code can be downloaded directly by pressing "Download FW Code".

Figure 8:

Firmware Download Window



4 Summary / Results

4.1 Verify Code Executing Properly

- Read registers 0x38 and 0x40 in the RAM memory, either by menu items Tools-RAM Memory or by the CPU Values window.
- 0x38 will show the current counter status, 0x40 should display the debug value (e.g. 0x101010)

Figure 9: CPU Values WIndow



Of course, monitoring the signal at GPIO0 is the final verification. In this example, the GPIO0 is set every 15 measurements.





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5 Revision Information

Changes from previous version to current revision v1-01

Page

Initial version for release

• Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.

Correction of typographical errors is not explicitly mentioned.

6 Legal Information

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